

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD70N10S3-12	**Issued**	29. August 2013
MA#	MA000427278		
Package	PG-TO252-3-11	**Weight***	372.18 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.755	1.55	1.55	15463	15463
leadframe	non noble metal	iron	7439-89-6	0.234	0.06		630	
	inorganic material	phosphorus	7723-14-0	0.070	0.02		189	
	non noble metal	copper	7440-50-8	234.187	62.95	63.03	629220	630041
wire	non noble metal	aluminium	7429-90-5	3.920	1.05	1.05	10534	10534
encapsulation	organic material	carbon black	1333-86-4	1.209	0.32		3247	
	plastics	epoxy resin	-	21.150	5.68		56826	
	inorganic material	silicondioxide	60676-86-0	98.497	26.46	32.46	264647	324720
leadfinish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10049	10049
plating	non noble metal	nickel	7440-02-0	0.091	0.02		244	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	245
solder	non noble metal	tin	7440-31-5	0.067	0.02		179	
	noble metal	silver	7440-22-4	0.083	0.02		224	
	non noble metal	lead	7439-92-1	3.181	0.85	0.89	8549	8949
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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